

NUMBER 178323

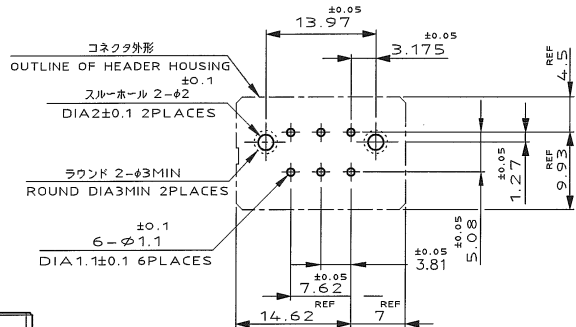
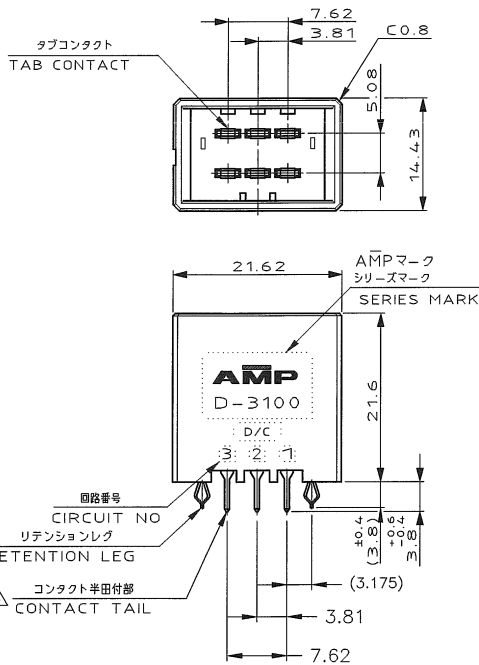


METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-J
REV.10/83



推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN LEAD PLATED
- FINISH (RETENTION LEG): TIN PLATED
- FINISH (CONTACT TAIL): OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
膜厚: 0.38μm MIN 全めっき
- めっき: コンタクト: 全面Ni下地
膜厚: 0.76μm MIN 全めっき
- めっき: コンタクト: 全面Ni下地
膜厚: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土に半田めっき

△	△	178323-5
△	△	178323-3
△	△	178323-2
(FINISH)		製品番号 (PART NO.)

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WIRE RANGE				INSULATION DIA		NAME	
D REVISED FJDN-0939-03 TS S.H. 02				-		DOUBLE ROW (D-3100)	
C REVISED FJDN-0937-03 TS S.M. 03				-		DYNAMIC CONN. 6POS. VERTICAL HDR. ASS'Y	
B REVISED FJDN-0838-94 NM S.M. 77				-		-	
A REDRAWN WITH CHANGE FJDN-0480-94 NM S.M. 92				-		-	
LTR REVISION RECORD DR CHK DATE				MATERIAL SEE NOTE		FINISH SEE NOTE	
DR. 15 FEB 91 N. Matsuzawa				DR. 15 FEB 91 N. Matsuzawa		APP. 23 MAY 91 S. MAMBE	
CHK. 21 MAY 91 N. Matsuzawa				APP. 23 MAY 91 S. MAMBE		-	
				GENERAL TOLERANCES		SIZE LOC NUMBER	
				100% ±0.3		A3 J C-178323	
				300% ±0.4		SCALE 2-1 REV. D SHEET 1 OF 1	
				50% ±0.5			
				25% ±0.5			

(CUSTOMER DRAWING) 顧客用図面